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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
Charles C.C. Lee
Chi-Hsi Wu

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
Name: Taiwan Semiconductor Manufacturing Co., Ltd.
Internal Address: _____
Street Address: No. 121, Park Avenue 3,
Science-Based Industrial Park
City: Hsin-Chu, Taiwan State: _____ Zip: 300-77
Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____
Execution Date: _____

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: _____
A. Patent Application No.(s) B. Patent No.(s)
10375489
Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: David M. O'Dell
Internal Address: _____
Street Address: Haynes and Boone, LLP
901 Main Street, Suite 3100
City: Dallas State: TX Zip: 75202

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41).....\$ 40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:
(Attach duplicate copy of this page if paying by deposit account)

03/04/2003
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
David M. O'Dell Signature Date 2-27-03
Name of Person Signing
Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

ASSIGNMENT

WHEREAS, we

- (1) Charles C.C. Lee of No. 67-2, Jianguo St.
Jubei City, Hsin-Chu
Taiwan 302, R.O.C.
- (2) Chi-Hsi Wu of No. 26, Alley 862
Nan-Da Rd.
Hsin-Chu
Taiwan 300, R.O.C.

have invented certain improvements in

**A METAL-INSULATOR-METAL DEVICE STRUCTURE INSERTED INTO A
LOW K MATERIAL AND THE METHOD FOR MAKING SAME**

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Inc., ("TSMC"), No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal,

substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name:

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Dated: 1/21/2003

Cheng-Chie Lee
Inventor Signature

Dated: 1/21/2003

Hao Yi Tsai
Witness Signature
Witness Name: _____

Second Inventor Name:

Chi-Hsi Wu

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Taiwan 300, R.O.C.

Dated: 1/21/2003

Chi-hsi Wu
Inventor Signature

Dated: 1/21/2003

Jiun-Lin Yeh
Witness Signature
Witness Name: _____